

Notification about the transfer of the semiconductor business

The semiconductor business of Panasonic Corporation was transferred on September 1, 2020 to Nuvoton Technology Corporation (hereinafter referred to as "Nuvoton"). Accordingly, Panasonic Semiconductor Solutions Co., Ltd. became under the umbrella of the Nuvoton Group, with the new name of Nuvoton Technology Corporation Japan (hereinafter referred to as "NTCJ").

In accordance with this transfer, semiconductor products will be handled as NTCJ-made products after September 1, 2020. However, such products will be continuously sold through Panasonic Corporation.

Publisher of this Document is NTCJ.

If you would find description "Panasonic" or "Panasonic semiconductor solutions", please replace it with NTCJ.

※ Except below description page

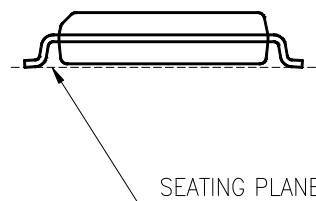
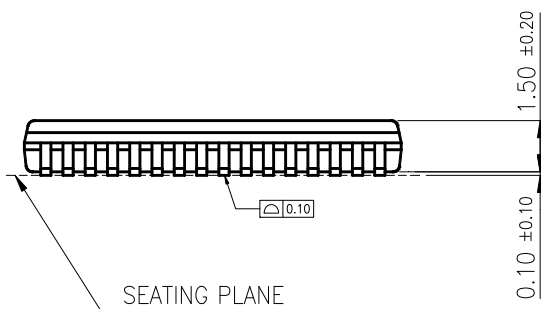
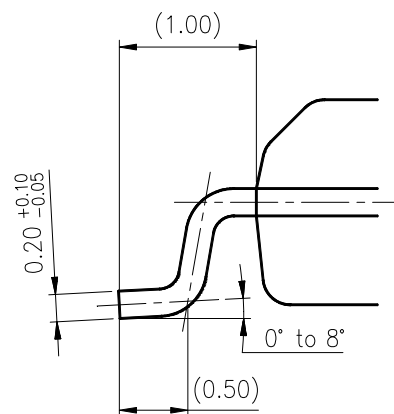
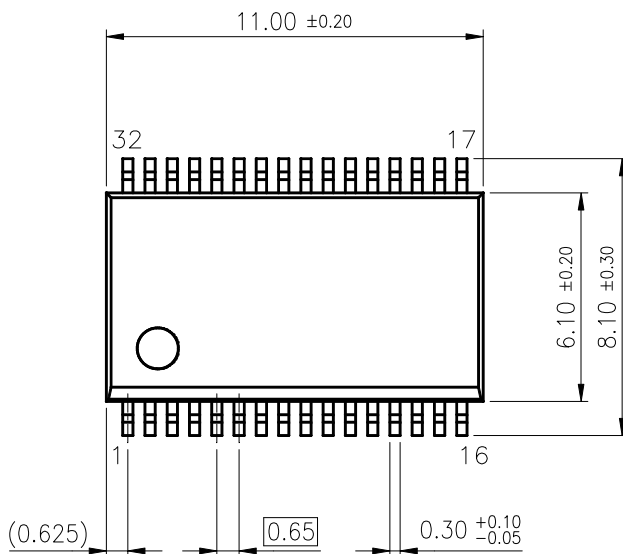
"Request for your special attention and precautions in using the technical information and semiconductors described in this book"

Nuvoton Technology Corporation Japan

1. Outline Drawing

Unit:mm

Package Code : SSOP032-P-0300B

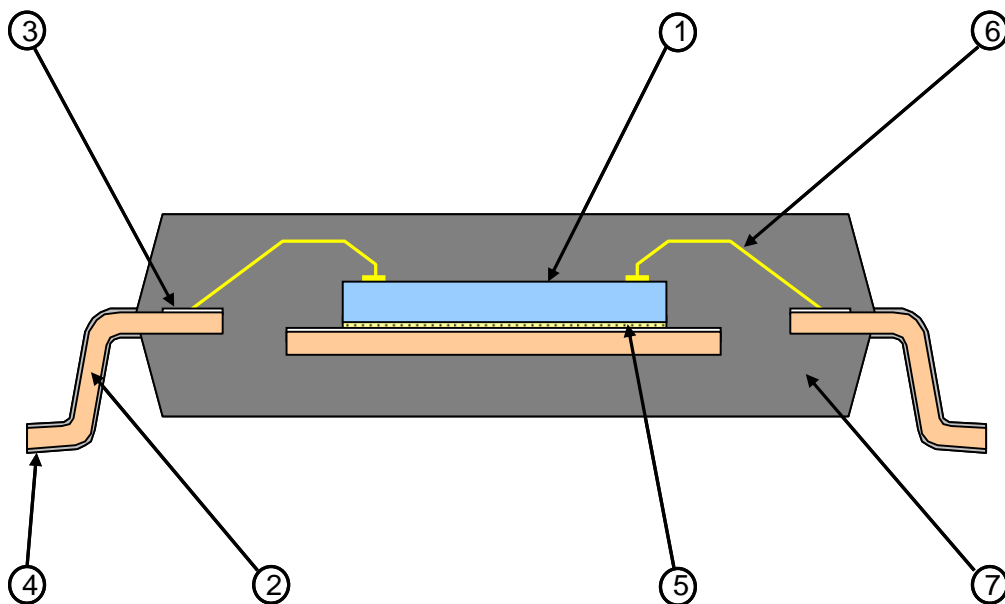


Body Material	: Epoxy Resin
Lead Material	: Cu Alloy
Lead Finish Method	: SnBi Plating

2. Package Structure (Technical Report : Reference Value)

Package Code : SSOP032-P-0300B

Chip Material	Si	①	
Leadframe material	Cu alloy	②	
Inner lead surface	Ag plating	③	
Outer lead surface	SnBi plating	④	
Chip mount	Method	Resin adhesive method	⑤
	Material	Adhesive material	
Wirebond	Method	Thermo-compression bonding	⑥
	Material	Au	
Molding	Method	Transfer molding	⑦
	Material	Epoxy resin	
Mass	250 mg		



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